

# SPECIFICATION (Reference sheet)

- Supplier : Samsung electro-mechanics
- Product : Multi-layer Ceramic Capacitor

- Samsung P/N : **CL03C120JA3ANNC**
- Description : **CAP, 12pF, 25V, ±5%, C0G, 0201**

## A. Samsung Part Number

**CL**   **03**   **C**   **120**   **J**   **A**   **3**   **A**   **N**   **N**   **C**  
 ①   ②   ③   ④   ⑤   ⑥   ⑦   ⑧   ⑨   ⑩   ⑪

|                         |                                       |                   |                         |  |  |  |  |  |  |  |
|-------------------------|---------------------------------------|-------------------|-------------------------|--|--|--|--|--|--|--|
| ① Series                | Samsung Multi-layer Ceramic Capacitor |                   |                         |  |  |  |  |  |  |  |
| ② Size                  | 0201 (inch code)                      | L: 0.6 ± 0.03 mm  | W: 0.3 ± 0.03 mm        |  |  |  |  |  |  |  |
| ③ Dielectric            | C0G                                   | ⑧ Inner electrode | Pd                      |  |  |  |  |  |  |  |
| ④ Capacitance           | 12 pF                                 | Termination       | Ag                      |  |  |  |  |  |  |  |
| ⑤ Capacitance tolerance | ±5 %                                  | Plating           | Sn 100% (Pb Free)       |  |  |  |  |  |  |  |
| ⑥ Rated Voltage         | 25 V                                  | ⑨ Product         | Normal                  |  |  |  |  |  |  |  |
| ⑦ Thickness             | 0.3 ± 0.03 mm                         | ⑩ Special         | Reserved for future use |  |  |  |  |  |  |  |
|                         |                                       | ⑪ Packaging       | Cardboard Type, 7" reel |  |  |  |  |  |  |  |

## B. Samsung Reliability Test and Judgement condition

|                                  | Performance                                                                                      | Test condition                                                                   |
|----------------------------------|--------------------------------------------------------------------------------------------------|----------------------------------------------------------------------------------|
| Capacitance                      | Within specified tolerance                                                                       | 1MHz±10%      0.5~5Vrms                                                          |
| Q                                | 640 min                                                                                          |                                                                                  |
| Insulation Resistance            | 10,000Mohm or 500Mohm·μF<br>Whichever is Smaller                                                 | Rated Voltage      60~120 sec.                                                   |
| Appearance                       | No abnormal exterior appearance                                                                  | Microscope (×10)                                                                 |
| Withstanding Voltage             | No dielectric breakdown or mechanical breakdown                                                  | 300% of the rated voltage                                                        |
| Temperature Characteristics      | C0G<br>(From -55℃ to 125℃, Capacitance change should be within ±30PPM/℃)                         |                                                                                  |
| Adhesive Strength of Termination | No peeling shall be occur on the terminal electrode                                              | 200g·F, for 10±1 sec.                                                            |
| Bending Strength                 | Capacitance change :<br>within ±5% or ±0.5pF whichever is larger                                 | Bending to the limit (1mm)<br>with 1.0mm/sec.                                    |
| Solderability                    | More than 75% of terminal surface is to be soldered newly                                        | SnAg3.0Cu0.5 solder<br>245±5℃, 3±0.3sec.<br>(preheating : 80~120℃ for 10~30sec.) |
| Resistance to Soldering heat     | Capacitance change :<br>within ±2.5% or ±0.25pF whichever is larger<br>Tan δ, IR : initial spec. | Solder pot : 270±5℃, 10±1sec.                                                    |

|                                    | Performance                                                                                                                                                                  | Test condition                                                                                                                                                                    |
|------------------------------------|------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|-----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| <b>Vibration Test</b>              | Capacitance change :<br>within $\pm 2.5\%$ or $\pm 0.25\mu\text{F}$ whichever is larger<br>Tan $\delta$ , IR : initial spec.                                                 | Amplitude : 1.5mm<br>From 10Hz to 55Hz (return : 1min.)<br>2hours $\times$ 3 direction (x, y, z)                                                                                  |
| <b>Moisture Resistance</b>         | Capacitance change :<br>within $\pm 7.5\%$ or $\pm 0.75\mu\text{F}$ whichever is larger<br>Q : 140 min<br>IR : 500Mohm or 25Mohm $\cdot \mu\text{F}$<br>Whichever is Smaller | With rated voltage<br>40 $\pm$ 2 $^{\circ}\text{C}$ , 90~95%RH, 500+12/-0hrs                                                                                                      |
| <b>High Temperature Resistance</b> | Capacitance change :<br>within $\pm 3\%$ or $\pm 0.3\mu\text{F}$ whichever is larger<br>Q : 305 min<br>IR : 1000Mohm or 50Mohm $\cdot \mu\text{F}$<br>Whichever is Smaller   | With 200% of the rated voltage<br>Max. operating temperature<br>1000+48/-0hrs                                                                                                     |
| <b>Temperature Cycling</b>         | Capacitance change :<br>within $\pm 2.5\%$ or $\pm 0.25\mu\text{F}$ whichever is larger<br>Tan $\delta$ , IR : initial spec.                                                 | 1 cycle condition<br>Min. operating temperature $\rightarrow 25^{\circ}\text{C}$<br>$\rightarrow$ Max. operating temperature $\rightarrow 25^{\circ}\text{C}$<br><br>5 cycle test |

#### C. Recommended Soldering method :

Reflow ( Reflow Peak Temperature : 260+0/-5 $^{\circ}\text{C}$ , 10sec. Max )

 Product specifications included in the specifications are effective as of March 1, 2013.  
Please be advised that they are standard product specifications for reference only.  
We may change, modify or discontinue the product specifications without notice at any time.  
So, you need to approve the product specifications before placing an order.  
Should you have any question regarding the product specifications,  
please contact our sales personnel or application engineers.